东莞市高钺达电子有限公司

DONGGUAN GAOYUEDA ELECTRONICS CO.,LTD

承　　认　　书
SPECIFICATION FOR APPROVAL

Customer　：_____

Description　：NANO SIM 卡座有柱|无柱

Part No.　：NOS11-S1F1-2000-A|NOS21-S1F1-2000-A

Customer P/N：_____

高钺达电子有限公司			客　　户	
工程承认章			工程承认章	
品管承认章			品管承认章	

TAIWAN FACTORY:協昌精密工業股份有限公司
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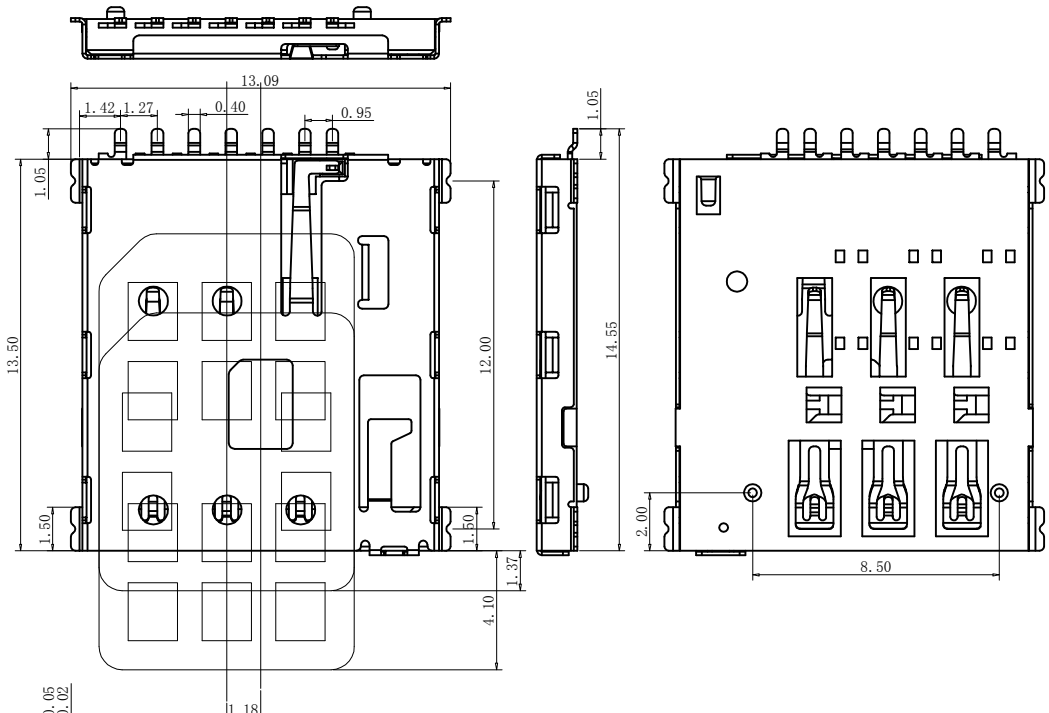
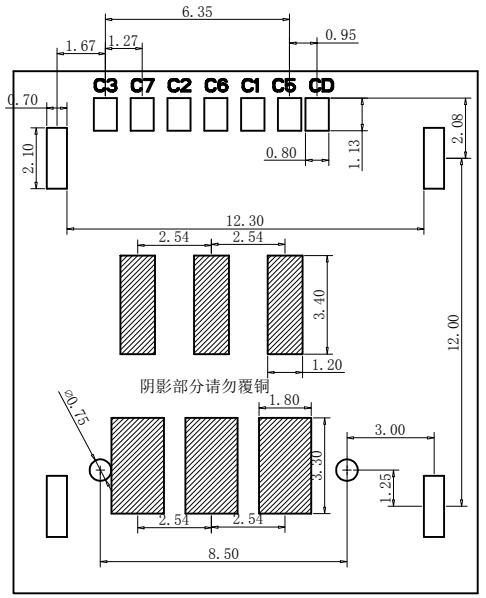
TEL:02-27884666　FAX：02-26535492
http:www.twshetime.com
CHINA FACTORY:东莞市高钺达电子科技有限公司
地址:东莞市虎门镇路东长元一路 2 号
TEL: 0769-85108085　FAX: 0769-6891569
E-mail:szgaosuda@163.com

REV.	DESCRIPTION	APPD	DATE





NOS11-S1F1-2000-A

1 有柱
2 无柱

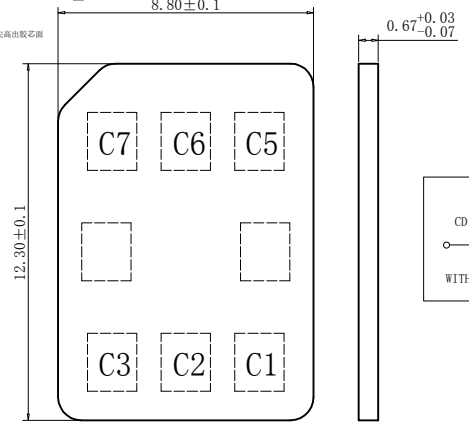
1)MATERIAL:
HOUSING:LCP S475 UL 94V-0
CONTACT:C5191
SHELL:SUS304-H

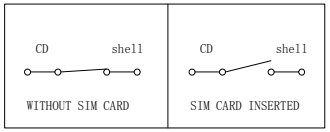
2)FINISH:
CONTACT:GOLD FLASH PLATED ON CONTACT AREA;
GOLD FLASH PLATED ON SOLDER TAILS,

3)ELECTRICAL CHARACTERISTICS
RATING CURRENT : 0.5A MAX.
CONTACT RESISTANCE :50 mΩ MAX
DIELECTRIC WITHSTANDING : 500V AC MIN.
INSULATION RESISTANCE: 1000 MΩ MIN.

4)MECHANICAL CHARACTERISTICS
MATING CYCLE :3000 CYCLES

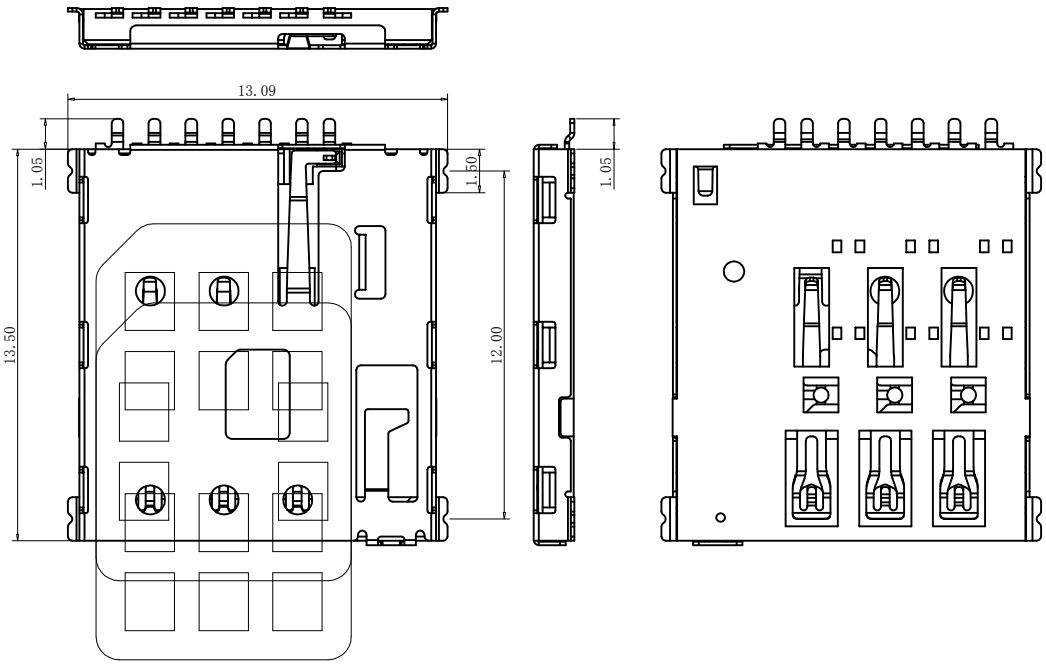
SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O

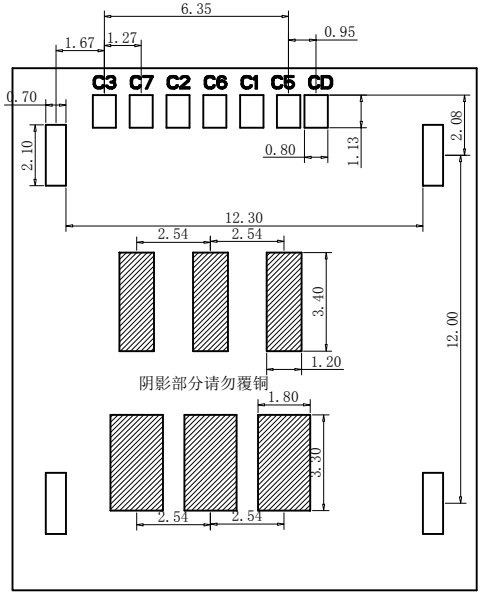




PART NO: NOS11-S1F1-2000-A		MATERIAL:	东莞市高铖达电子科技有限公司
LOT NO:		FINSH:	
UNIT: MM	SIZE: A4	COLOR:	TITLE: NANO SIM PUSN 卡座
TOLERANCES: X.X=±0.35 X.XX=±0.25 X.XXX=±0.15	GENERAL ANGLE: X.X=±3.0° X.XX=±2.0°	DR: 刘 静	DWG NO: FP-090012 REV: A
		CHK:	
		APP:	SCALE: 1:1 SHEET: 1 OF 1

REV.	DESCRIPTION	APPD	DATE





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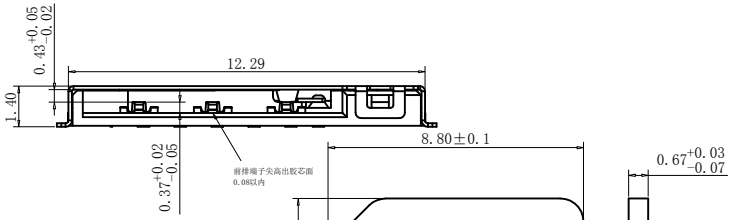
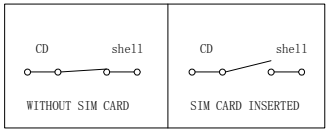
MATING CYCLE :3000 CYCLES



NOS21-S1F1-2000-A
1 有柱
2 无柱

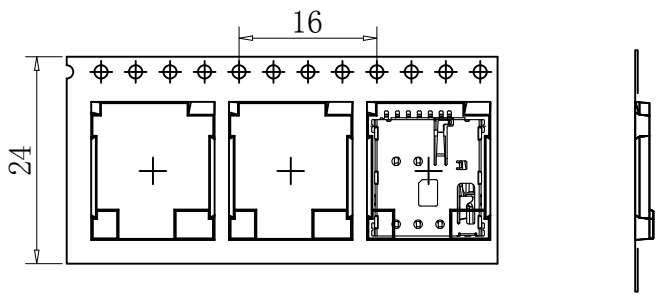
SIM pin Assignment	
PIN#	Name
C1	VCC
C2	RST
C3	CLK
C5	GND
C6	VPP
C7	I/O



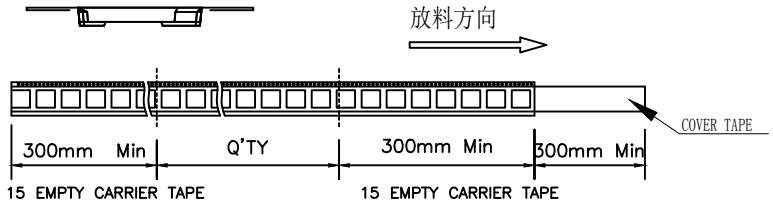
PART NO: NOS21-S1F1-2000-A		MATERIAL:	东莞市高铖达电子科技有限公司
LOT NO:		FINSH:	
UNIT: MM	SIZE: A4	COLOR:	TITLE: NANO SIM PUSN 卡座
TOLERANCES: X.X=±0.35 X.XX=±0.25 X.XXX=±0.15	GENERAL ANGLE: X.X=±3.0° X.XX=±2.0°	DR: 刘 静	DWG NO: FP-090012 REV: A
		CHK:	SCALE: 1:1 SHEET: 1 OF 1
		APP:	

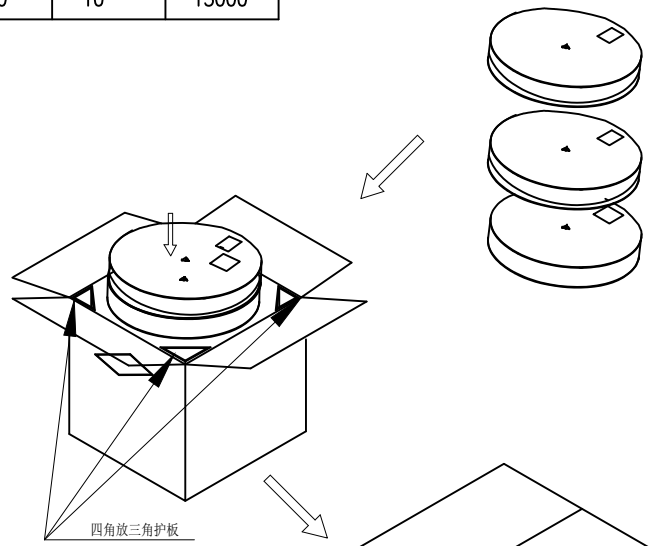
RoHS

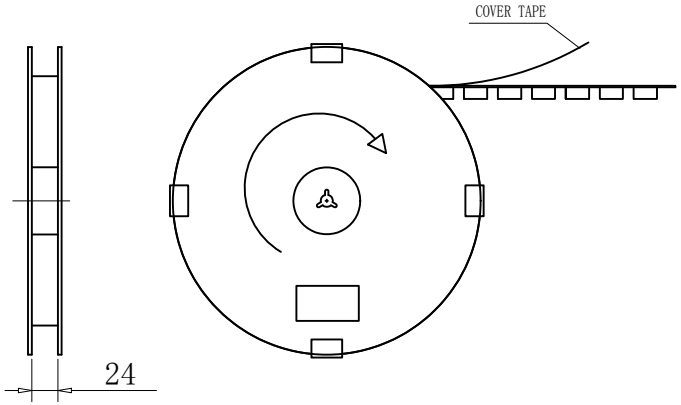
REV.	DESCRIPTION	APPD	DATE



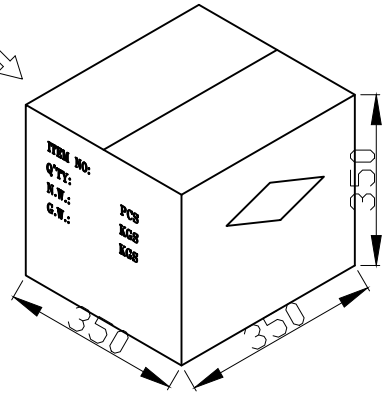
QTY/REEL	REEL/CARTON	QTY/CARTON
1500	10	15000







1, 每盘前后空5PSC，中间包装1500PCS
2, 每箱10盘，共15000PCS。
3, 纸箱四角放脚柱。



PART NO: NOSxx-S1F1-2000-A		MATERIAL:	东莞市高钺达电子科技有限公司
LOT NO:		FINSH:	
UNIT: MM	SIZE: A4	COLOR:	TITLE: NANO SIM PUSN 卡座
TOLERANCES: X. X=±0.35 X. XX=±0.25 X. XXX=±0.15	GENERAL ANGLE: X. X=±3.0° X. XX=±2.0°	DR: 刘 静	
		CHK:	DWG NO: FP-090012 REV: A
		APP:	SCALE: 1:1 SHEET: 1 OF 1

SIM SOCKET CONN.

1. SCOPE

This specification covers the sim socket connector.

1.2. QUALIFICATION

Tests are to be performed by the procedures stated in this specification. All inspections shall be conducted using the inspections plan for this product and product drawing.

2. APPLICABLE DOCUMENT

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, latest edition of the specification applies. In the event of conflict between requirements of this specification and product drawing, product drawing shall take precedence.

3. REQUIREMENTS

3.1.DESIGN AND CONSTRUCTION

Product shall be of the design, construction and physical dimensions specified on the applicable product drawing.

3.2.MATERIALS

A. Housing：High Temperature,Thermoplastic UL94V-0,Black color

B. Contact：Copper alloy, Gold plating with Nickel underplated.

C. Shell：Stainless steel , Plated SOLDER TAIL AREA.

3.3.RATINGS

A. Voltage: **30** VAC rms.

B. Current: **0.5** A Max

C. Temperature: - **20** °C to +**65**°C

3.4.STORAGE TEMPERATURE:

Storage temperature range is the range of ambient temperature at which the connector housing can be stored without load **-10℃ ~ +40℃**

3.5.PERFOMANCE REQUEIREMENT AND TEST DESCRIPTION

The product shall be designed to meet the electrical, mechanical and environmental performance requirements specified in Figure 1. All tests shall be performed at ambient environmental conditions per AMP Specification 109-1TEST REQUIREMENTS AND PROCEDURES SUMMARY.

3.6.TEST REQUIREMENTS AND PROCEDURES SUMMARY

Test Item		Requirement	Procedure
1	Examination of Product	Meets requirements of product drawing. No physical damage.	Visual inspection.
ELECTRICAL REQUIREMENT			
2	Contact Resistance	50 m Ohm Max(Initial) 100 m Ohm Max(Final) Detection switch resistance: Initial:200m Ohm Max After test:300m Ohm Max	Subject mated contacts assembled in housing to 20mV Max open circuit at 10mA Max.EIA-364-23A. MIL-STD-202:Test method for Electronic And Electrical Component Parts.
3	Dielectric withstanding Voltage	No creeping discharge or flashover shall occur. Current leakage: 0.5 mA MAX	500 VAC for 1minute Test between adjacent circuits of unmated connector. EIA-364-20A
4	Insulation Resistance	100 M Ohm Min.	Impressed voltage 250 VDC. Test between adjacent circuits of unmated connector. EIA-364-21A.
MECHANICAL REQUIREMENT			
5	Vibration	No evidence of physical damage Current discontinuity ≦ 10 μs Contact Resistance≦ 100mΩ	Frequency span：10 Hz ~ 55 Hz ~ 10 Hz (in 1 min.) This motion shall be applied for 6 hrs in each of 3 mutually perpendicular direction. Amplitude：1.52mm Max. EIA-364-28A
6	Mechanical Shock	Appearance : No damage, loose part nor crack Discontinuity: 10μs MAX Contact Resistance≦100mΩ	All contacts shall be connected in series and 5Volt DC 100mA shall be applied. Maximum acceleration: 490 m/s2 Half sine wave.(Duration: 11 ms) Direction: 3 directions (X,Y,Z) 3 times per each direction
7	Durability	No evidence of physical damage Contact Resistance≦ 100mΩ	Mate and un-mate connector assemblies for 3000 cycles at cycle rate of 600+/-50 cycles per hour if done EIA-RS-364-09A
8	Contact Normal Force	40gf /pin Min. After the durability: 25~35gf /pin Min	Measured by means of tensile force test equipment
9	Contact retention force	50gf /pin Min.	Measure the contact retention force with Tensile strength tester.

ENVIRONMENTAL REQUIREMENTS			
10	Humidity Test (Steady state)	No evidence of physical damage, Contact resistance ≦ 100 mΩ Insulation Resistance ≧ 1000 MΩ No evidence of discharge or flashes occur	samples assembly with P.C.B and without P.C.B Exposing in the test chamber at temperature of 40±2℃ with 90~95% RH for 96 hours. Then placed in ambient temperature for 1 ~ 2 hrs. EIA-RS-364-31A
11	Thermal Shock	No evidence of physical damage, Contact resistance ≦ 100 mΩ Insulation Resistance ≧ 1000 MΩ No evidence of discharge or flashes occur	Mated Connector -55+/-3℃(30 minutes),+5℃~+35℃(5 minutes) +85+/-2℃(30 minutes), +5℃~+35℃(5 minutes) Perform this a cycle, repeat 5 cycles EIA-364-32C
12	Temperature Life	No evidence of physical damage, Contact resistance ≦ 100 mΩ Insulation Resistance ≧ 1000 MΩ No evidence of discharge or flashes occur	Unmated connector. 85+2℃ for 96 hours
PHYSICAL			
13	Solderability	No evidence of physical damage Coverage 95% Min.	5 ~ 10 sec. dipped into soldering flux Then subject leads of connector to solder bath , Sn63, at 245 ± 5 ℃ for 10 ± 0.5 seconds EIA-RS-364-52
14	Salt Spray	No detrimental corrosion allowed in contact area. Contact resistance ≦ 100 mΩ	samples assembly with P.C.B Salt water concentration : 5 % weight ratio Exposing in the test chamber at temperature of 35±2℃ for 16 hours Then placed in ambient temperature for 1 ~ 2 hrs EIA-RS-364-26A
15	Resistance to soldering heat	No evidence of physical damage	Test condition for reflow soldering(Fig 1)

3.7. PRODUCT QUALIFICATION AND REQUALIFICATION TEST

	Test or Examination	Test Group(a)										
		A	B	C	D	E	F	G	H	I	J	K
1	Examination of Product	1,5	1, 5	1,5	1, 8	1, 7	1,6	1,4	1,3			
2	Contact Resistance	2,4	2,4	2, 4	2, 6	2,6	2,5					
3	Insulation Resistance				3,5							
4	Dielectric withstanding Voltage			,	7							
5	Mechanical Shock						4					
6	Contact normal force					3,5						
7	Contact retention force							3				
8	Durability					4						
9	Vibration						3					
10	Humidity				4							
11	Salt Spray		3									
12	Temperature Life			3								
13	Thermal Shock	3										
14	Solderability								2			
15	Hot air reflow or IR reflow for SMD curing process							2				
	Numbers(pcs) (sample quantity)	5	5	5	5	5	5	5	5			

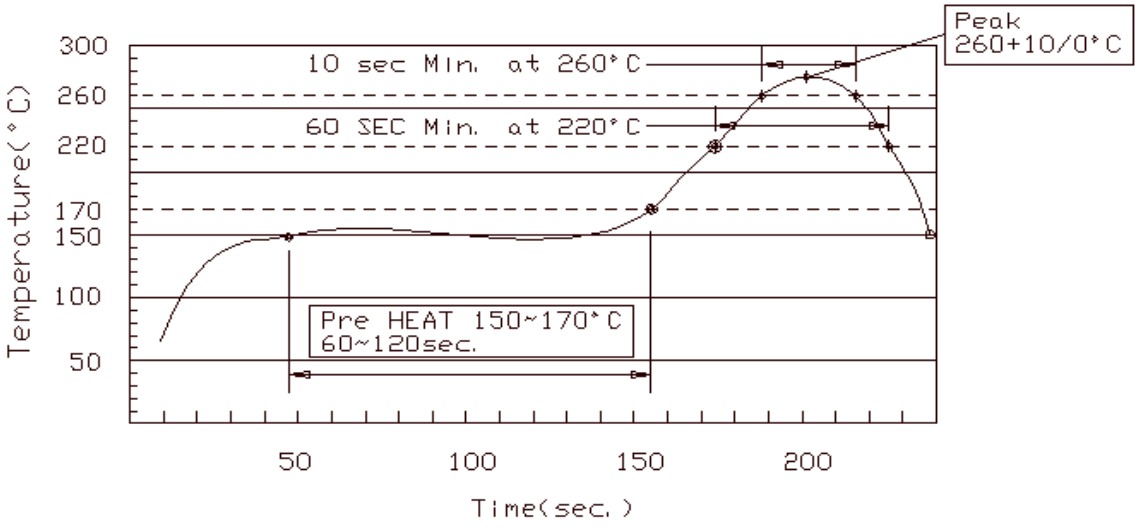


Fig.1 Temperature profile of Infrared Reflow Soldering for evaluation